

Transistor

Switching (30V, $\pm 10A$)

RSS100N03

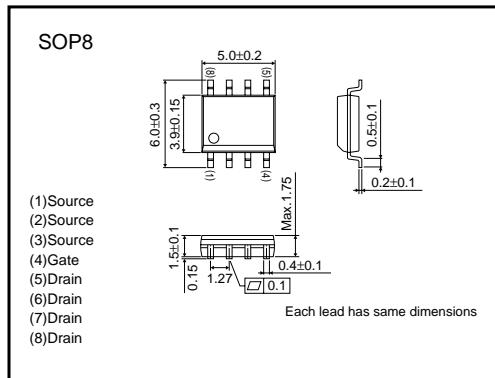
●Features

- 1) Low on-resistance.
- 2) Built-in G-S Protection Diode.
- 3) Small and Surface Mount Package (SOP8).

●Applications

Power switching, DC/DC converter.

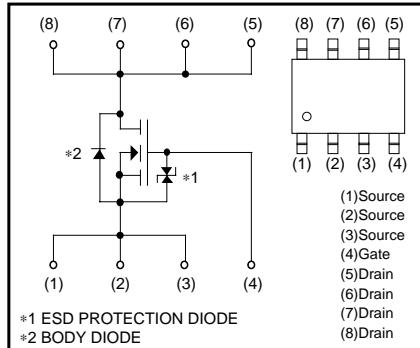
●External dimensions (Units : mm)



●Structure

•Silicon N-channel MOS FET

●Equivalent circuit



*A protection diode is included between the gate and the source terminals to protect the diode against static electricity when the product is in use. Use the protection circuit when the fixed voltages are exceeded.

●Absolute maximum ratings ($T_a=25^\circ C$)

Parameter		Symbol	Limits	Unit
Drain-source voltage		V_{DSS}	30	V
Gate-source voltage		V_{GSS}	20	V
Drain current	Continuous	I_D	± 10	A
	Pulsed	I_{DP}	± 40	A
Source current (Body diode)	Continuous	I_S	1.6	A
	Pulsed	I_{SP}	6.4	A
Total power dissipatio ($T_c=25^\circ C$)		P_D	2	W
Channel temperature		T_{ch}	150	$^\circ C$
Strage temperature		T_{stg}	-55~+150	$^\circ C$

*1 $P_w \leq 10\mu s$, Duty cycle $\leq 1\%$

Transistor

● Thermal resistance (Ta=25°C)

Parameter	Symbol	Limits	Unit
Channel to ambient	R _{th} (ch-A)	62.5	°C / W

● Electrical characteristics (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Gate-source leakage	I _{GSS}	—	—	10	μA	V _{GS} =20V, V _{DS} =0V
Drain-source breakdown voltage	V _{(BR) DSS}	30	—	—	V	I _D =1mA, V _{GS} =0V
Zero gate voltage drain current	I _{DSS}	—	—	10	μA	V _{DS} =30V, V _{GS} =0V
Gate threshold voltage	V _{GS (th)}	1.0	—	2.5	V	V _{DS} =10V, I _D =1mA
Static drain-source on-starte resistance	R _{DS (on)}	—	9.5	13.0	mΩ	I _D =±10A, V _{GS} =10V
		—	12.5	17.2	mΩ	I _D =±10A, V _{GS} =4.5V
		—	13.5	18.5	mΩ	I _D =±10A, V _{GS} =4V
Forward transfer admittance	Y _{fs}	6.0	—	—	S	I _D =±10A, V _{DS} =10V
Input capacitance	C _{iss}	—	1070	—	pF	V _{DS} =10V
Output capacitance	C _{oss}	—	320	—	pF	V _{GS} =0V
Reverse transfer capacitance	C _{rss}	—	200	—	pF	f=1MHz
Tum-on delay time	t _{d (on)}	—	10	—	ns	I _D =5A, V _{DD} =15V
Rise time	t _r	—	16	—	ns	V _{GS} =10V
Tum-off delay time	t _{d (off)}	—	55	—	ns	R _L =3.0Ω
Fall time	t _f	—	24	—	ns	R _{GS} =10Ω
Total gate charge	Q _g	—	14	—	nC	V _{DD} =15V
Gate-source charge	Q _{gs}	—	2.7	—	nC	V _{GS} =5V
Gate-drain charge	Q _{gd}	—	5.3	—	nC	I _D =±10A

*Pulsed

● Body diode characteristics (Source-Drain Characteristics) (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Forward voltage	V _{SD}	—	—	1.2	V	I _S =6.4A, V _{GS} =0V

*Pulsed

● Electrical characteristic curves

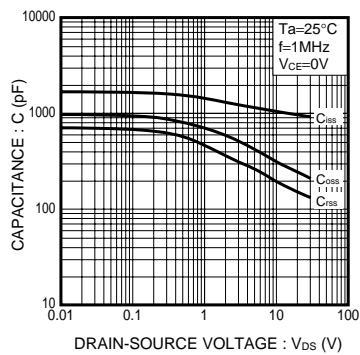


Fig.1 Typical Capacitance vs. Drain-Source Voltage

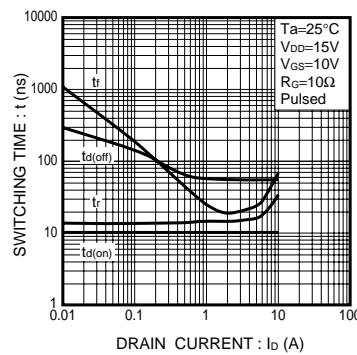


Fig.2 Switching Characteristics

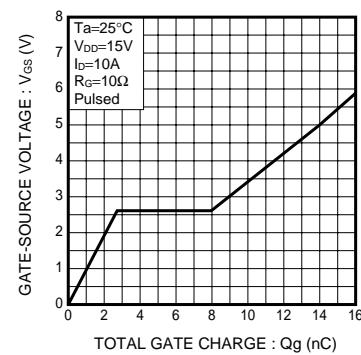


Fig.3 Dynamic Input Characteristics

Transistor

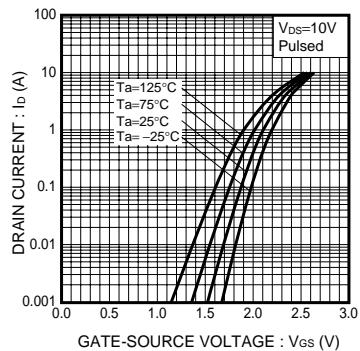


Fig.4 Typical Transfer Characteristics

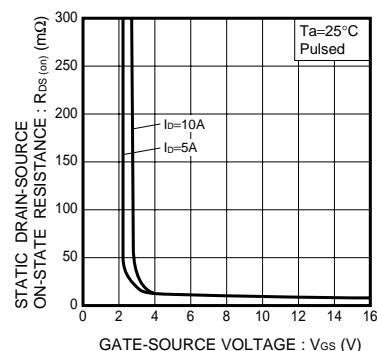


Fig.5 Static Drain-Source
On-State Resistance vs.
Gate-Source Voltage

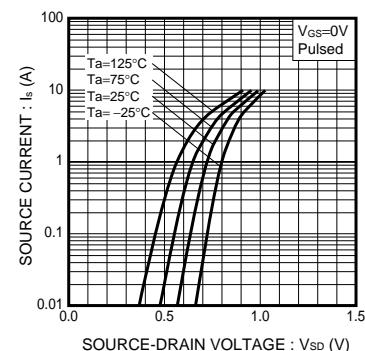


Fig.6 Source Current vs.
Source-Drain Voltage

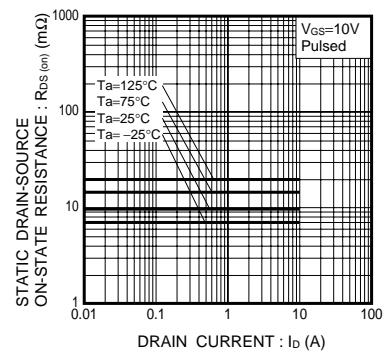


Fig.7 Static Drain-Source
On-State Resistance
vs. Drain Current (I)

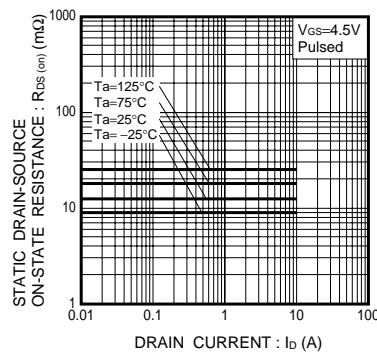


Fig.8 Static Drain-Source
On-State Resistance
vs. Drain Current (II)

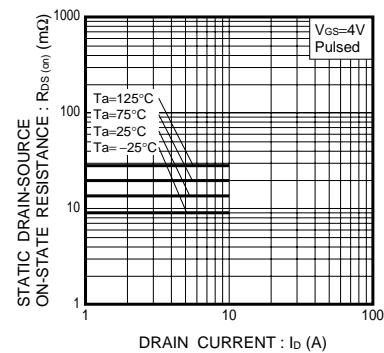


Fig.9 Static Drain-Source
On-State Resistance
vs. Drain Current (III)